

P-Channel Enhancement Mode MOSFET

DESCRIPTION

The HG9435 is the P-Channel logic enhancement mode power field effect transistors are produced using high cell density , DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance.

These devices are particularly suited for low voltage application , notebook computer power management and other battery powered circuits where high-side switching .

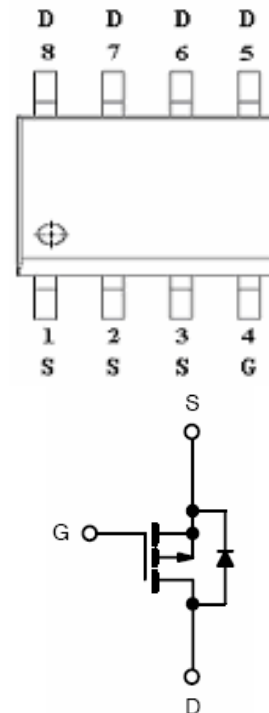
FEATURES

- ◆ -30V/-5.7A, $R_{DS(ON)} = 60m\Omega @ V_{GS} = -10V$
- ◆ -30V/-5.0A, $R_{DS(ON)} = 70m\Omega @ V_{GS} = -6V$
- ◆ -30V/-4.4A, $R_{DS(ON)} = 80m\Omega @ V_{GS} = -4.5V$
- ◆ Super high density cell design for extremely low $R_{DS(ON)}$
- ◆ Exceptional on-resistance and maximum DC current capability
- ◆ SOP – 8P package design

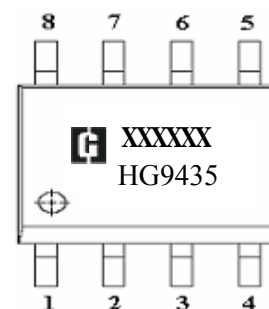
APPLICATIONS

- Power Management in Note book
- Portable Equipment
- Battery Powered System
- DC/DC Converter
- Load Switch
- DSC
- LCD Display inverter

PIN CONFIGURATION(SOP – 8P)



PART MARKING



PIN DESCRIPTION

Pin	Symbol	Description
1	S	Source
2	S	Source
3	S	Source
4	G	Gate
5	D	Drain
6	D	Drain
7	D	Drain
8	D	Drain

ABSOLUTE MAXIMUM RATINGS

($T_A=25^{\circ}\text{C}$ Unless otherwise noted)

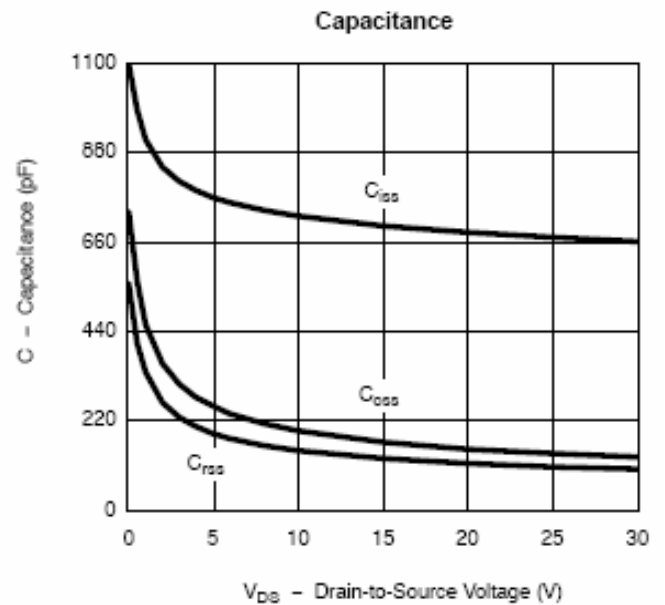
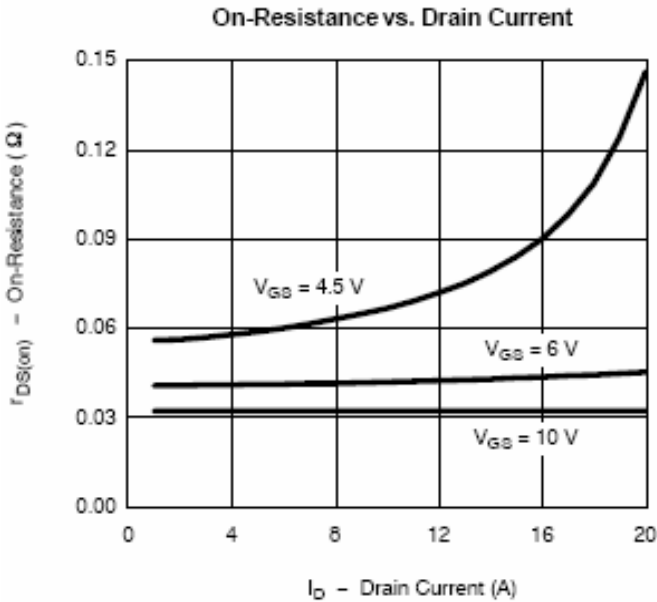
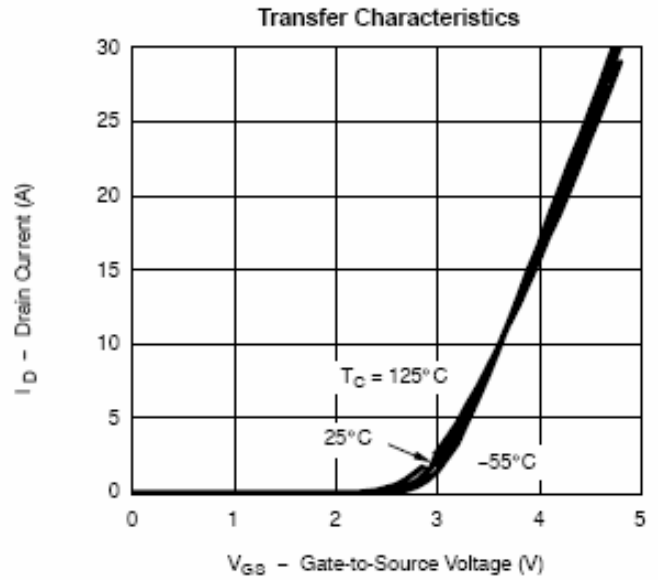
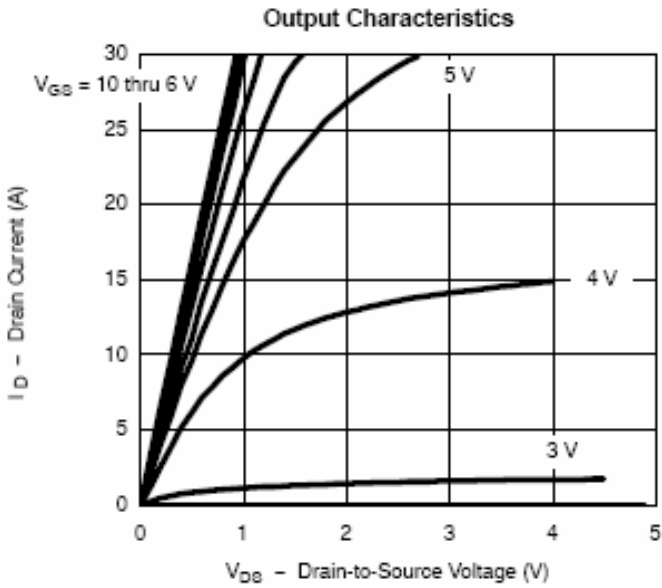
Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V_{DSS}	-30	V
Gate –Source Voltage	V_{GSS}	± 20	V
Continuous Drain Current($T_J=150^{\circ}\text{C}$)	I_D	$T_A=25^{\circ}\text{C}$	-6.8
		$T_A=70^{\circ}\text{C}$	-4.6
Pulsed Drain Current	I_{DM}	-30	A
Continuous Source Current(Diode Conduction)	I_S	-2.3	A
Power Dissipation	P_D	$T_A=25^{\circ}\text{C}$	2.8
		$T_A=70^{\circ}\text{C}$	1.8
Operating Junction Temperature	T_J	-55/150	$^{\circ}\text{C}$
Storage Temperature Range	T_{STG}	-55/150	$^{\circ}\text{C}$
Thermal Resistance-Junction to Ambient	$R_{\theta JA}$	70	$^{\circ}\text{C}/\text{W}$

ELECTRICAL CHARACTERISTICS

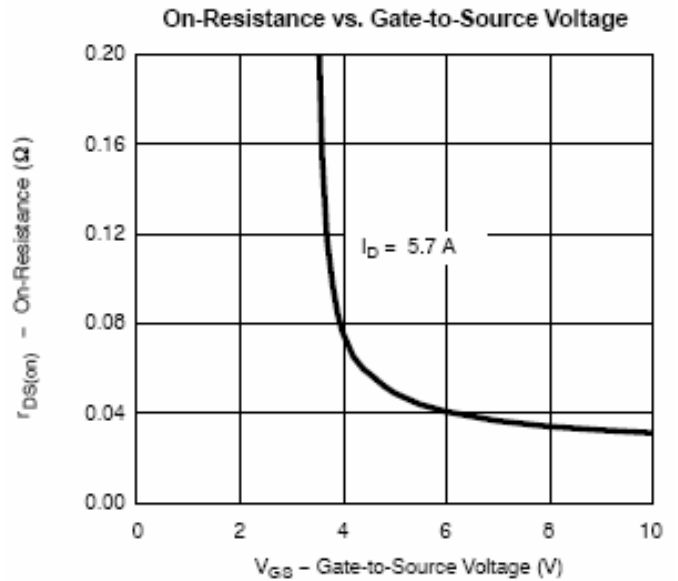
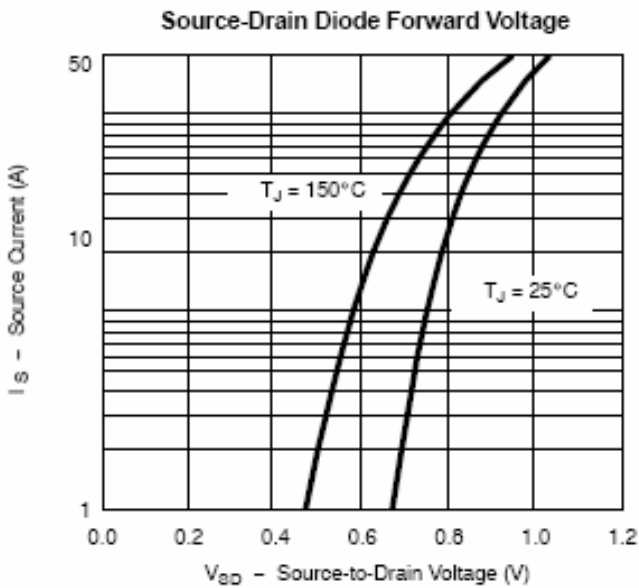
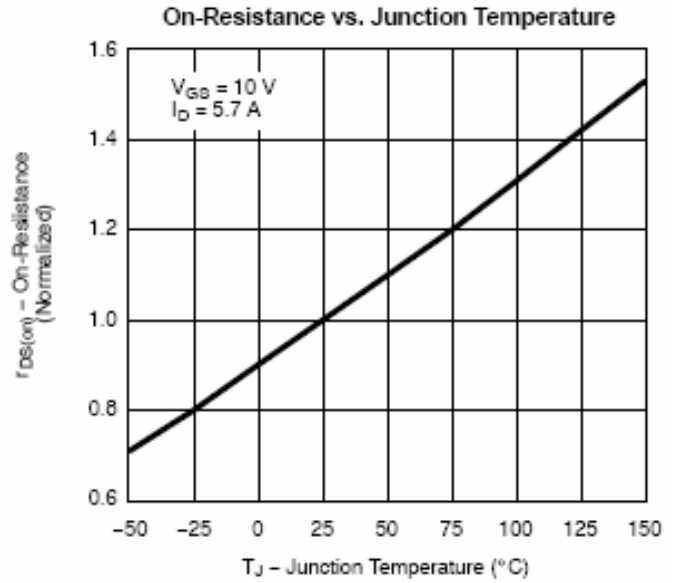
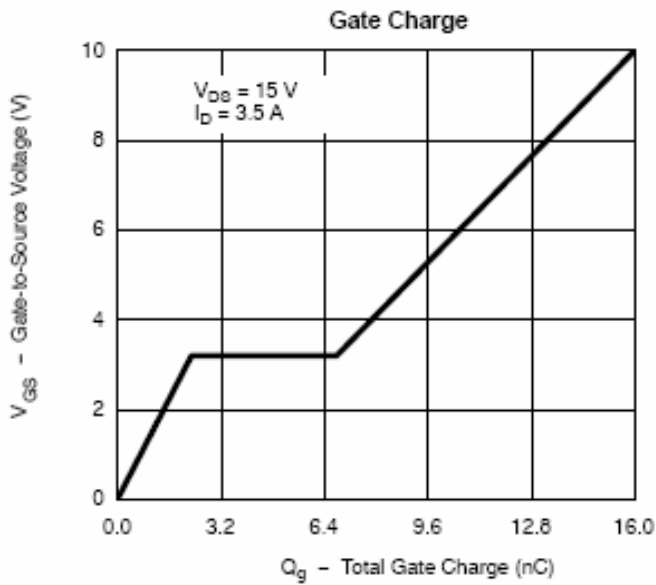
(T_A=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =-250uA	-30			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250uA	-1.0		-3.0	
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-24V, V _{GS} =0V			-1	uA
		V _{DS} =-24V, V _{GS} =0V T _J =85°C			-5	
On-State Drain Current	I _{D(on)}	V _{DS} = -5V, V _{GS} =-4.5V	-10			A
Drain-Source On-Resistance	R _{DSS(on)}	V _{GS} =-10V, I _D =-5.7A		0.048	0.060	Ω
		V _{GS} =-6.0V, I _D =-5.0A		0.054	0.070	
		V _{GS} =-4.5V, I _D =-4.4A		0.058	0.080	
Forward Transconductance	g _{fs}	V _{DS} =-15V, I _D =-5.7A		13		S
Diode Forward Voltage	V _{SD}	I _S =-2.3A, V _{GS} =0V		-0.8	-1.2	V
Dynamic						
Total Gate Charge	Q _g	V _{DS} =-15V, V _{GS} =-10V I _D = -3.5A		16	24	nC
Gate-Source Charge	Q _{gs}			2.3		
Gate-Drain Charge	Q _{gd}			4.5		
Input Capacitance	C _{iss}	V _{DS} =-15V, V _{GS} =0V f=1MHz		680		pF
Output Capacitance	C _{oss}			120		
Reverse Transfer Capacitance	C _{rss}			75		
Turn-On Time	t _{d(on)}	V _{DD} =-15V, R _L =15Ω I _D =-1.0A, V _{GEN} =-10V R _G =6Ω		14	25	nS
	t _r			15	26	
Turn-Off Time	t _{d(off)}			42	70	
	t _f			30	50	

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

